

Abstract of the Disclosure

A lead frame apparatus for holding IC packages during IC package processing is provided. The lead frame apparatus comprises a substantially
5 flat thin strip of conductive material having substantially parallel sides and square ends forming the lead frame apparatus, a strip of adhesive material adhered to one surface of lead frame apparatus, the overall dimensions of the strip substantially the same as the overall dimensions of the lead frame apparatus, a plurality of die-attach pads arranged on the non-adhesive
10 surface of the lead frame apparatus, the pads for receiving IC packages for encapsulation by molding, and at least one geometric area of material alteration formed in the conductive material forming the lead frame, the area located substantially at either frame end, wherein a user accesses the strip of adhesive material through utilization of the material alteration for the
15 purpose of removing the adhesive material from the surface of the lead frame.

20